

Application No. 10/784,517

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings of claims in the application:

1. (Currently Amended) A method of making photosensitive chips for use in an imaging apparatus, comprising ~~the steps of:~~

providing an integrated circuit wafer, the wafer comprising a first chip area defined in a main surface of the wafer, the first chip area including structure related to a first photosite, and a groove defined in the wafer, the groove defining at least one edge of the first chip area;

providing a light-transmissive planar layer over the main surface, the planar layer forming a planar surface substantially parallel with the main surface, the planar layer extending over the groove;

providing a filtering layer over the planar layer, the filtering layer extending over the first photosite and over the groove; and

dicing the wafer along the groove.

2. The method of **claim 1**, the planar layer comprising acrylic.

3. (Cancelled)

4. (Cancelled)

5. (Currently Amended) The method of ~~claim 3~~ **claim 1**, the filtering layer comprising acrylic.

6. (Currently Amended) The method of **claim 1**, further comprising the ~~step of~~ providing in the chip area a ridge defined on the main surface between the photosite and the groove.

7. (Cancelled)